



## Material Content Data Sheet



Sales Product Name	BGA 915N7 E6327			Issued		29. August 2013		
MA#	MA000943978							
Package	PG-TSNP-7-6			Weight*		2.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.108	5.01	5.01	50090	50090
leadframe	non noble metal	zinc	7440-66-6	0.002	0.09		881	
	non noble metal	tin	7440-31-5	0.002	0.11		1101	
	non noble metal	chromium	7440-47-3	0.003	0.13		1322	
	non noble metal	copper	7440-50-8	0.939	43.72	44.05	437140	440444
wire	noble metal	gold	7440-57-5	0.025	1.16	1.16	11551	11551
encapsulation	organic material	carbon black	1333-86-4	0.005	0.21		2141	
	plastics	epoxy resin	-	0.133	6.21		62092	
	inorganic material	silicondioxide	60676-86-0	0.782	36.40	42.82	363986	428219
leadfinish	non noble metal	tin	7440-31-5	0.066	3.09	3.09	30865	30865
plating	noble metal	silver	7440-22-4	0.020	0.91	0.91	9149	9149
glue	plastics	epoxy resin	-	0.013	0.59		5937	
	noble metal	silver	7440-22-4	0.051	2.37	2.96	23745	29682
*deviation	< 10%	Sum in total:			100,00			1000000

### Important Remarks:

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